iC-LSHB

INCREMENTAL PHOTOSENSOR ARRAY



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FEATURES

Monolithic array of independent photosensors with excellent matching

Compact photosensor size of $800\,\mu m\ x\ 330\,\mu m$ enabling smaller encoder systems

Moderate track pitch for reasonable alignment tolerances Ultra low dark currents for operation to high temperature Low noise amplifiers with high transimpedance of typ. 1 $M\Omega$ Short-circuit-proof, low impedance voltage outputs for enhanced EMI tolerance

Space saving optoBGA and optoQFN package (RoHS compliant)

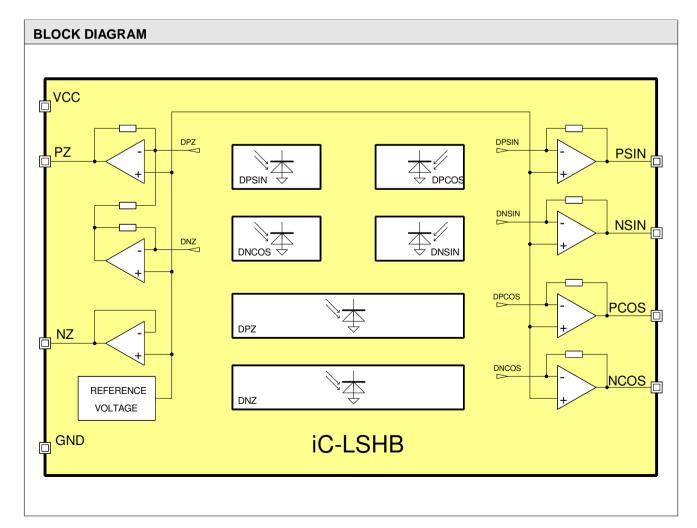
Low power consumption from single 4.5 V to 5.5 V supply Operational temperature range of -40 $^{\circ}$ C to +110 $^{\circ}$ C Available options

- reticle assembly, code discs
- customized COB modules

APPLICATIONS

Incremental rotary encoders Linear scales

PACKAGES 15-pin optoBGA 6.2 mm x 5.2 mm 32-pin optoQFN 5 mm x 5 mm x 0.9 mm



iC-LSHB

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DESCRIPTION

iC-LSHB is an optical sensor IC with 6 integrated photodiodes whose signal currents are converted into output voltages by low-noise transimpedance amplifiers.

The IC is well suited for the operation of interpolation circuits for linear or rotary incremental encoders with an index signal. iC-LSHB thus has a shamrock-style sensor layout of four photodiodes, each with an active area of $800\,\mu\text{m}$ x $330\,\mu\text{m}$. Both a positive and negative sine signal and a positive and negative cosine signal are generated from a single shared code track. The signal amplifier layout ensures excellent paired channel matching, reducing signal differences to an absolute minimum.

Two separate photodiodes, with active areas of $1720\,\mu m\ x\ 150\,\mu m$ apiece, are employed for the differential scanning of the index track and to generate the zero signal.

The spectral sensitivity ranges from visible to near infrared light, with the maximum sensitivity close to a wavelength of 680 nm.

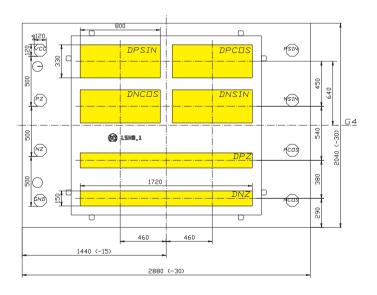
A high transimpedance gain of typically 1 M Ω generates output signals of a few hundret Millivolts already from illumination levels of 0.8 mW/cm².

A threefold intensity is sufficient when using iC-LSHB for encoder applications with typical disc and mask codes. Therefore, a relatively low LED current is enough to operate the sensor, proving beneficial to the life expectancy of the LED at high operating temperatures.

iC-LSHB is suitable for on-chip or LED-end mounting of the grating (reticle), so that the period count, signal waveform, phase shift and index marker code can be selected with flexibility.

PACKAGING INFORMATION

PAD LAYOUT (2.88 mm x 2.04 mm)



PAD FUNCTIONS No. Name Function

1 VCC +4.5..5.5 V Supply Voltage

2 PZ Zero Signal (Index)

3 NZ Reference Voltage Output

4 GND Ground

5 NCOS Cosine -

6 PCOS Cosine +

7 NSIN Sine -

8 PSIN Sine +

Notes: All outputs supply analog volt-

ages.

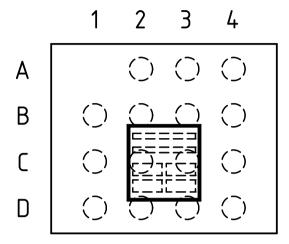
Dimension G4 is the reference radius of

the chip center.



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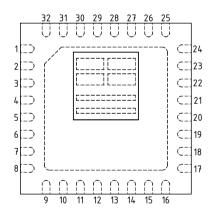
PIN CONFIGURATION oBGA LSH2C (6.2 mm x 5.2 mm)



PIN FUNCTIONS

No.	Name	Function
A2		
A3		
A4		
B1		
B2		
В3		
B4		
C1	NCOS	Cosine -
C2	PCOS	Cosine +
C3	NZ	Reference Voltage Output
C4	GND	Ground
D1	NSIN	Sine -
D2	PSIN	Sine +
D3	VCC	+4.55.5 V Supply Voltage
D4	PΖ	Zero Signal (Index)

PIN CONFIGURATION oQFN32-5x5 (5 mm x 5 mm)



PIN FUNCTIONS

NO.	Name	Function
1	n.c.	
2	VCC	+4.55.5 V Supply Voltage
3	PΖ	Zero Signal (Index)
4	NZ	Reference Voltage Output
5	GND	Ground
6-19	n.c.	
20	NCOS	Cosine -
21	PCOS	Cosine +
22	NSIN	Sine -
23	PSIN	Sine +
24-32	n.c.	

NB: All outputs supply analog voltages.

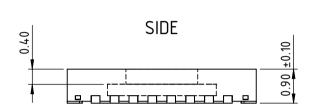
Pin numbers marked n.c. are not in use. The backside paddle is not intended as an electrical connection point; when used as shield a single link to GND is permissible.

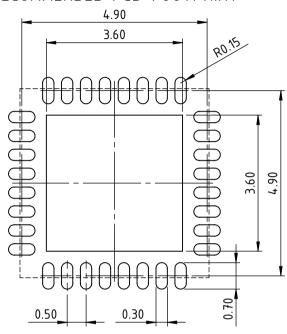


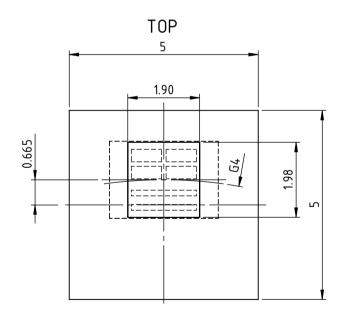
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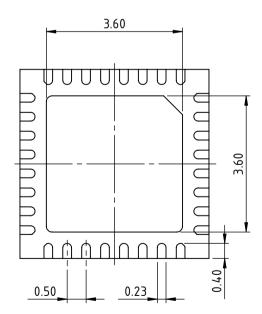
PACKAGE DIMENSIONS oQFN32-5x5

RECOMMENDED PCB-FOOTPRINT









BOTTOM

All dimensions given in mm. Tolerances of form and position according to JEDEC M0–220. Positional tolerance of sensor pattern: $\pm70\mu m$ / $\pm1^{\circ}$ (with respect to backside pad). G4: radius of chip center (refer to the relevant encoder disc and code description). Maximum molding excess $+20\mu m$ / $-75\mu m$ versus surface of glass/reticle.

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ABSOLUTE MAXIMUM RATINGS

These ratings do not imply operating conditions; functional operation is not guaranteed. Beyond these ratings device damage may occur.

Item	Symbol	Parameter	Conditions			Unit
No.				Min.	Max.	
G001	VCC	Voltage at VCC		-0.3	6	V
G002	I(VCC)	Current in VCC		-20	20	mA
G003	V()	Pin Voltage, all signal outputs		-0.3	VCC +	V
					0.3	
G004	I()	Pin Current, all signal outputs		-20	20	mA
G005	Vd()	ESD Susceptibility, all pins	HBM, 100 pF discharged through 1.5 kΩ		2	kV
G006	Tj	Junction Temperature		-40	150	°C
G007	Ts	Chip Storage Temperature		-40	150	°C

THERMAL DATA

Operating conditions: VCC = 4.5 V . . . 5.5 V

Item	Symbol	Parameter	Conditions				Unit
No.				Min.	Тур.	Max.	
T01	Та	Operating Ambient Temperature Range	package oBGA LSH2C, oQFN32-5x5 (extended temperature range on request)	-40		110	°C
T02	Ts	Storage Temperature Range	package oBGA LSH2C	-40		110	°C
T03	Tpk	Soldering Peak Temperature	package oBGA LSH2C				
			tpk < 20 s, convection reflow tpk < 20 s, vapor phase soldering TOL (time on label) 8 h; Please refer to customer information file No. 7			245 230	ဗိ
T04	Tpk	Soldering Peak Temperature	for details. package oQFN32-5x5;				
		Coldoning Feat Temperature	tpk < 20 s, convection reflow tpk < 20 s, vapor phase soldering MSL 5A (max. floor life 24 h at 30 °C and 60 % RH); Please refer to customer information file No. 7 for details.			245 230	ဗိ



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ELECTRICAL CHARACTERISTICS

Operating conditions: VCC = 4.5..5.5 V, Tj = -40..125 °C, unless otherwise stated

Item No.	Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Total	Device	,	,				
001	VCC	Permissible Supply Voltage		4.5		5.5	V
002	I(VCC)	Supply Current in VCC	no output load, photocurrents within linear operating range (no override)		6.5	12	mA
003	Vc()hi	Clamp-Voltage hi at all pins	I() = 4 mA			11	V
004	Vc()lo	Clamp-Voltage lo at all pins	I() = -4 mA	-1.2		-0.3	V
Photo	sensors						
101	λ ar	Spectral Application Range	$Se(\lambda ar) = 0.25 \times S(\lambda) max$	400		950	nm
102	λ pk	Peak Sensitivity Wavelength			680		nm
103	Aph()	Radiant Sensitive Area of DPSIN, DPCOS, DNSIN, DNCOS	0.8 mm x 0.33 mm		0.264		mm ²
104	Aph()	Radiant Sensitive Area of DPZ, DNZ	1.72 mm x 0.15 mm		0.258		mm ²
105	S(\lambda r)	Spectral Sensitivity	$\lambda_{\text{LED}} = 740 \text{nm}$ $\lambda_{\text{LED}} = 850 \text{nm}$		0.45 0.3		A/W A/W
107	E()mx	Irradiance For Maximum Signal Level	$\lambda_{\text{LED}} = 740 \text{nm}$, Vout() not yet saturated		1.7		mW/ cm ²
Photo	current Am	plifiers	,		'		
201	lph()	Permissible Photocurrent Operating Range		0		1120	nA
202	η ()r	Photo Sensitivity (light-to-voltage conversion ratio)	$\lambda_{LED} = 740nm$	0.2	0.3	0.5	V/µW
203	Z()	Equivalent Transimpedance Gain	Z = Vout() / Iph()	0.7	1.0	1.4	ΜΩ
204	TCz	Temperature Coefficient of Transimpedance Gain			-0.12		%/°C
209	ΔZ()pn	Transimpedance Gain Matching Of Paired Amplifiers	P channel vs. corresponding N channel	-0.2		0.2	%
210	ΔVout()pn	Signal Matching	no illumination, any output vs. any output	-35		35	mV
211	△Vout()pn	Signal Matching	no illumination, P output vs. corresponding N output	-2.5		2.5	mV
212	fc()hi	Cut-off Frequency (-3 dB)			400		kHz
213	VNoise()	RMS Output Noise	illuminated to 500 mV signal level above dark level, 500 kHz band width		0.5		mV
Signa	Outputs PS	SIN, NSIN, PCOS, NCOS, PZ					
301	Vout()mx	Permissible Maximum Output Voltage	illumination to E()mxr, linear gain	2.45	2.72	3.02	V
302	Vout()d	Dark Signal Level	no illumination, load 20 kΩ vs. +2 V	600	770	1000	mV
303	Vout()acmx	Maximum Signal Level	Vout()acmx = Vout()mx - Vout()d	1.48	1.96	2.35	V
304	Isc()hi	Short-circuit Current hi	load current to ground	100	420	800	μA
305	lsc()lo	Short-circuit Current lo	load current to IC	250	480	700	μA
306	Ri()	Internal Output Resistance	f = 1 kHz	70	110	180	Ω
307	ton()	Power-On Settling Time	$VCC = 0 V \rightarrow 5 V$			100	μs
Refer	ence Voltage	NZ					
401	VREF	Reference Voltage	I(VREF) = 0+1.6 mA	600	770	1000	mV
402	dVout()	Load Balancing	I(VREF) = 0+1.6 mA	-10		+10	mV
403	Isc()hi	Short-circuit Current hi	load current to ground	200	420	800	μA
404	lsc()lo	Short-circuit Current lo	load current to IC	2	4.5	10	mA

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APPLICATION HINTS

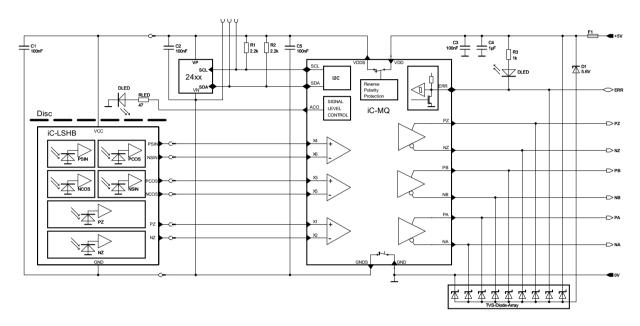


Figure 1: Example of incremental encoder with RS422 output

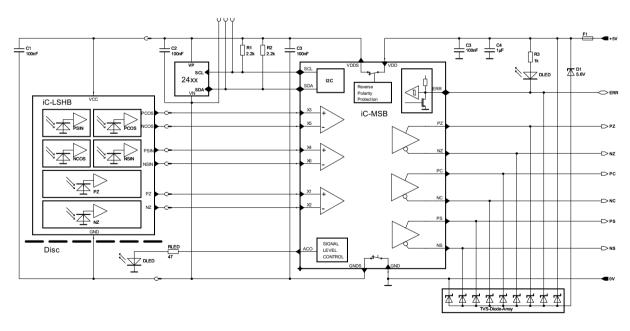


Figure 2: Example of sine encoder with 1 Vpp output



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DESIGN REVIEW: Notes On Chip Functions

iC-LSHB 2				
No.	Function, Parameter/Code	Description and Application Hints		
1		Please refer to former datasheet release B1.		

Table 4: Notes on chip functions regarding iC-LSHB chip release 2.

iC-LSHB Z		
No.	Function, Parameter/Code	Description and Application Hints
1		No further notes at time of printing.

Table 5: Notes on chip functions regarding iC-LSHB chip release Z.

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ORDERING INFORMATION

Туре	Package	Options	Order Designation
iC-LSHB	optoBGA 6.2 mm x 5.2 mm	glass lid reticle LSHB2R 42-1024 reticle LSHB4R 42-4096 reticle LSHB5R 26-3600	iC-LSHB OBGA LSH2C iC-LSHB OBGA LSH2C-2R iC-LSHB OBGA LSH2C-4R iC-LSHB OBGA LSH2C-5R
	32-pin optoQFN, 5 mm x 5 mm thickness 0.9 mm	glass lid reticle LSHB2R 42-1024	iC-LSHB oQFN32-5x5 iC-LSHB oQFN32-5x5-2R
Code Disc		1024 PPR, OD/ID ∅42/18 mm, glass	LSHB2S 42-1024
		4096 PPR, OD/ID ∅42/18 mm, glass	LSHB4S 42-4096
		3600 PPR, OD/ID Ø26/14 mm, glass	LSHB5S 26-3600

For technical support, information about prices and terms of delivery please contact:

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